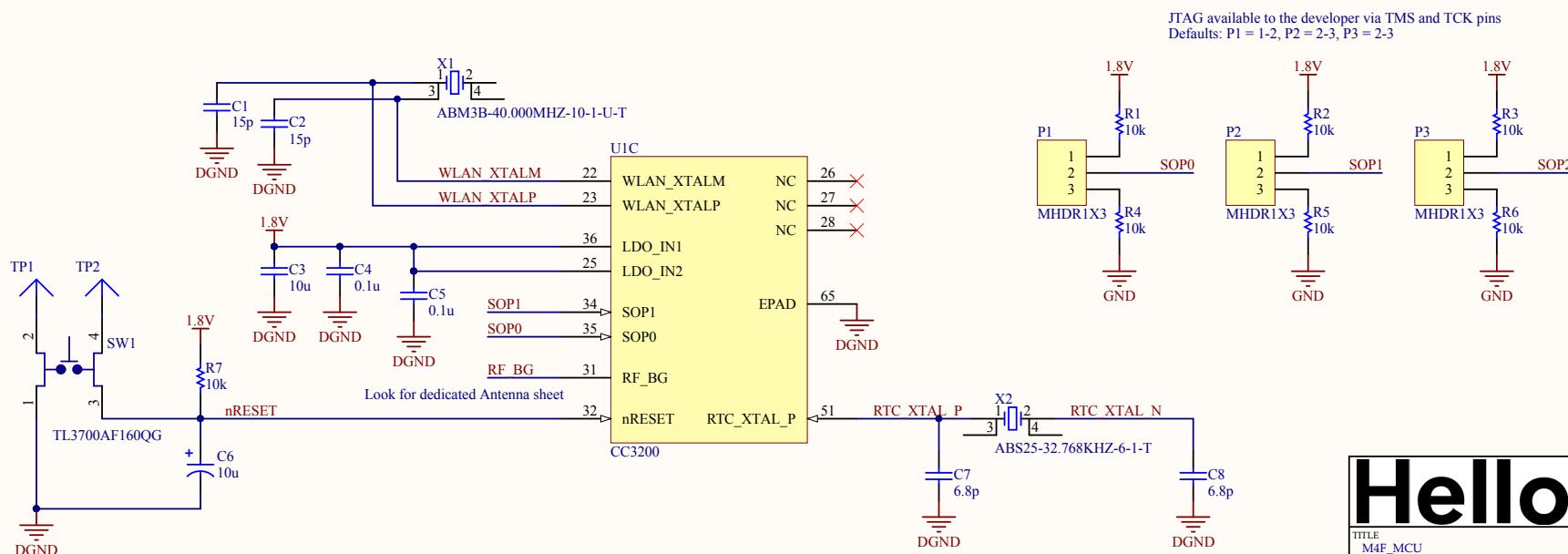
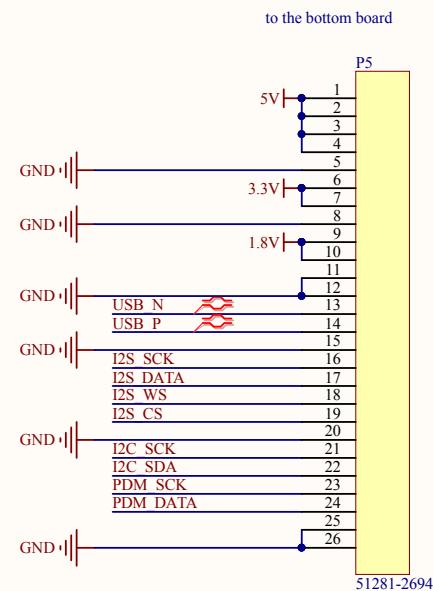
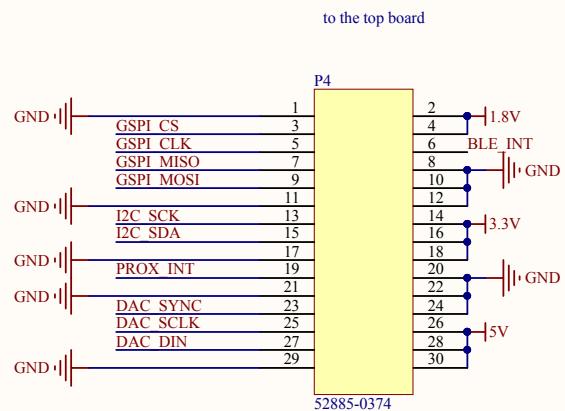
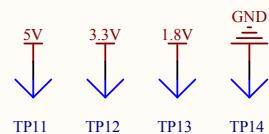
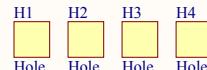
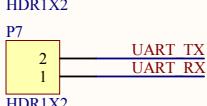
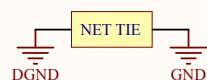
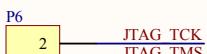


pin 52 can be used as GPIO when getting 32 kHz clk from another IC
pin 18 is not usable as GPIO





programming / debugging connectors



Hello

| TITLE | REV |
|-----------------|----------|
| Morpheus_middle | 1 |
| DATE | DRAWN BY |
| 6/2/2014 | D. Fusi |

SHEET 2 OF 6

A

A

B

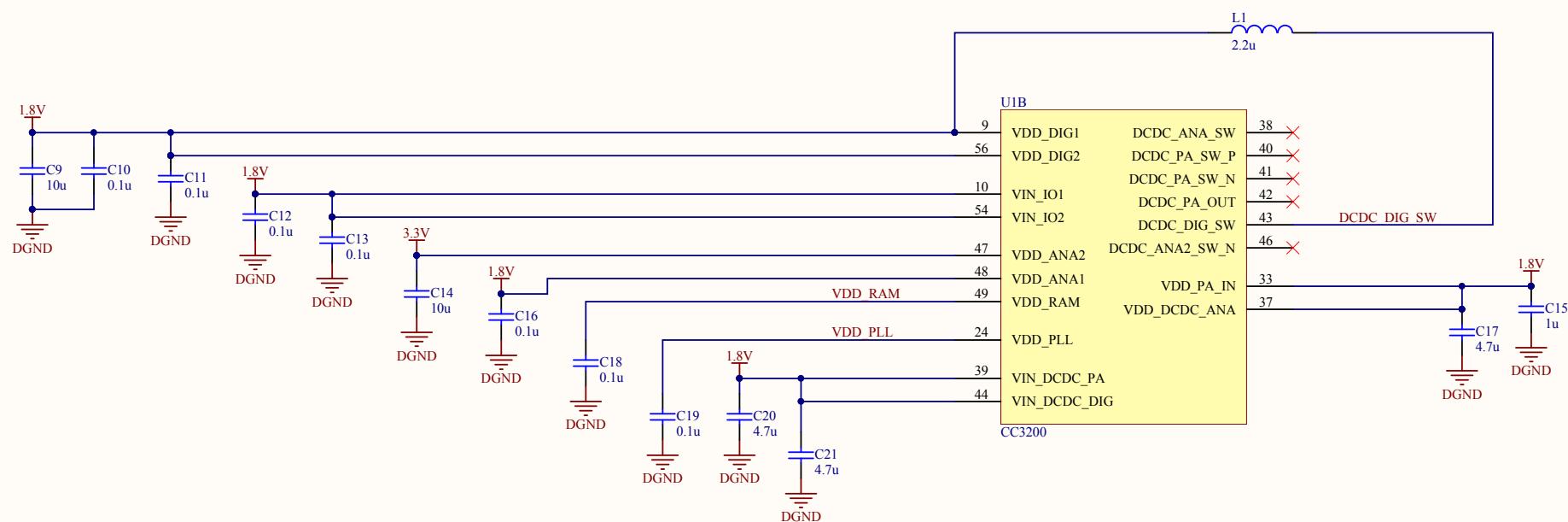
B

C

C

D

D



Hello

| TITLE | REV |
|---------------|----------|
| M4F MCU Power | 1 |
| DATE | DRAWN BY |
| 5/30/2014 | D. Fusi |

A

A

B

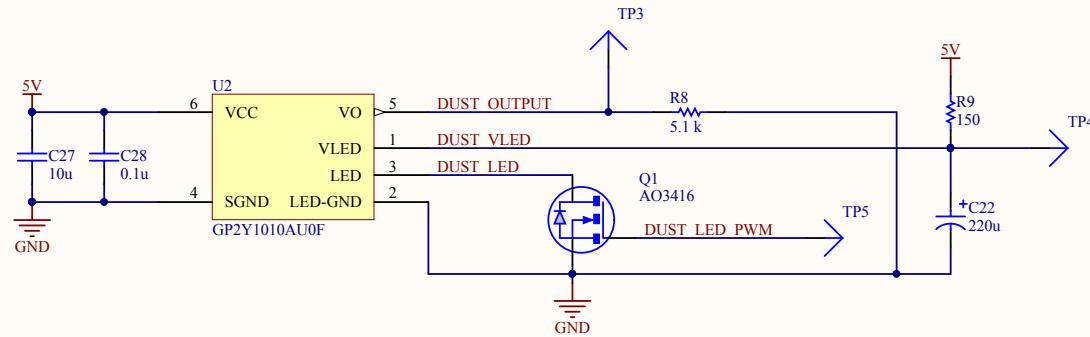
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C

C

D

D



A

A

B

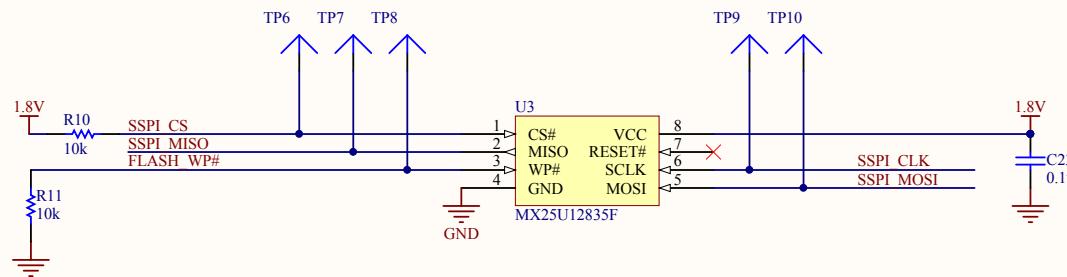
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C

C

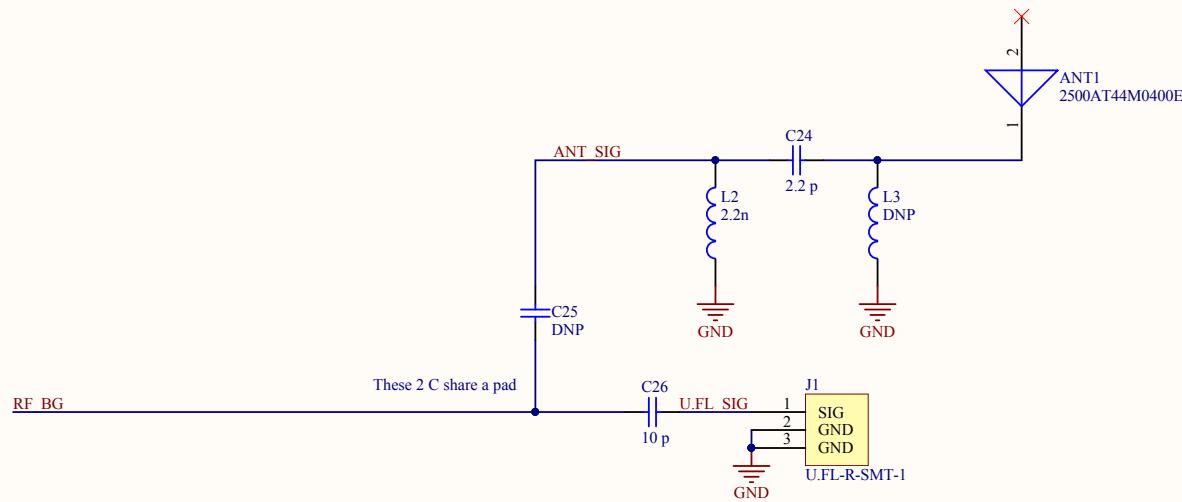
D

D



A

A



B

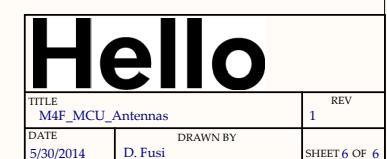
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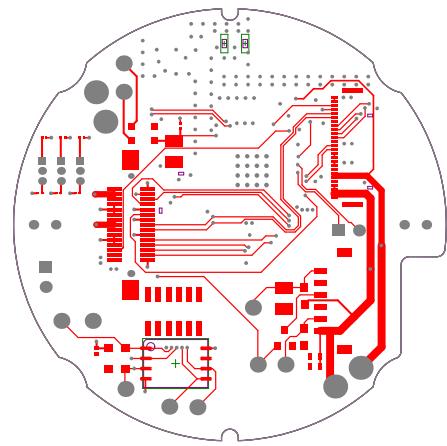
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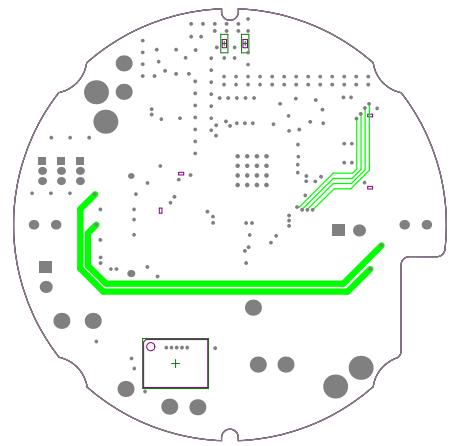
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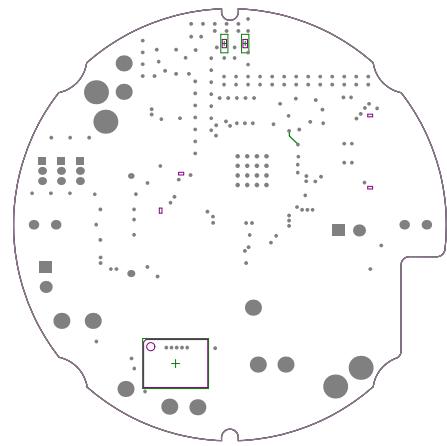
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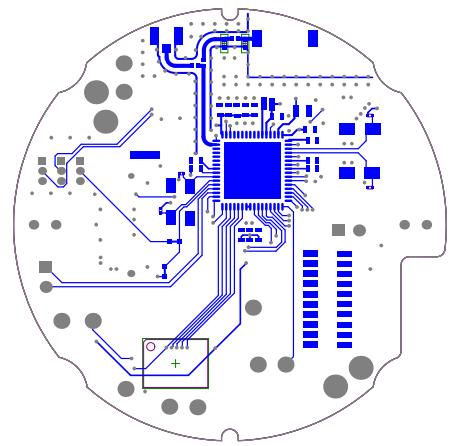
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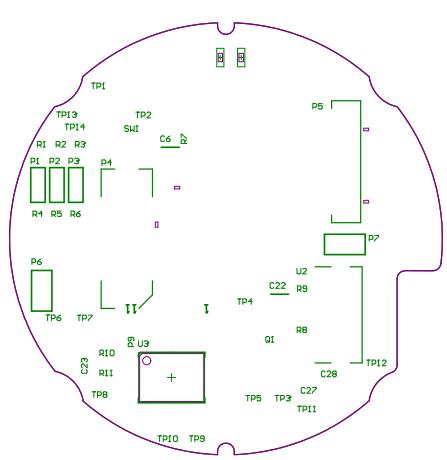


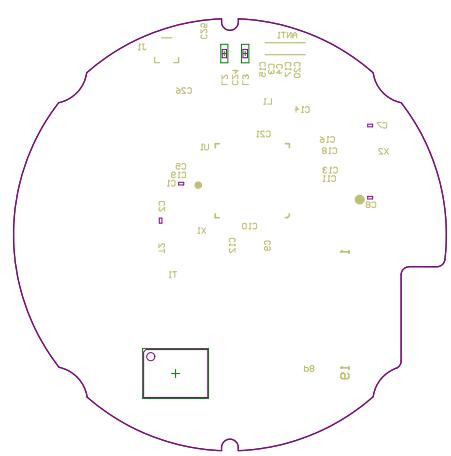


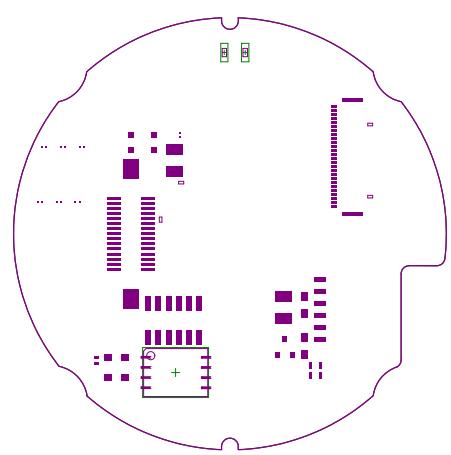


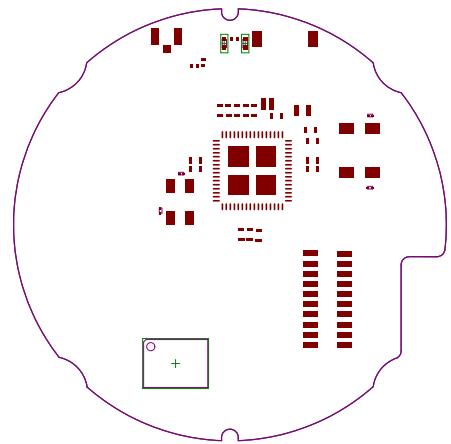


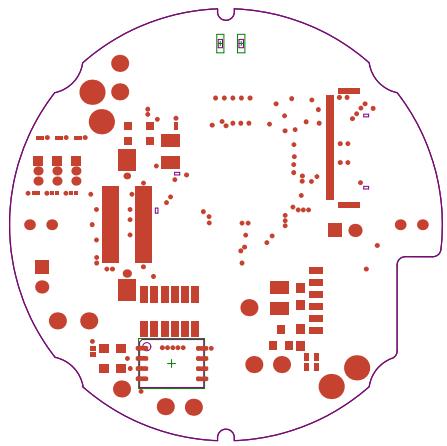


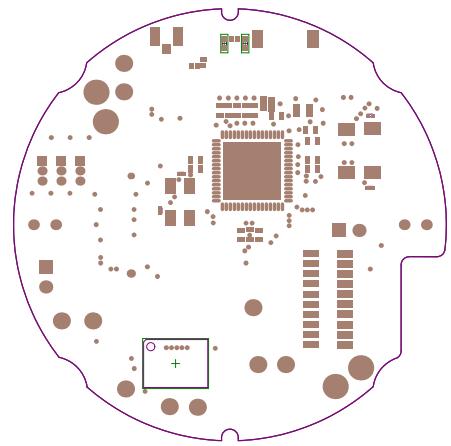


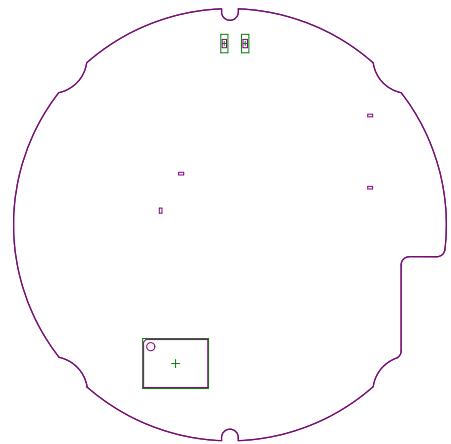


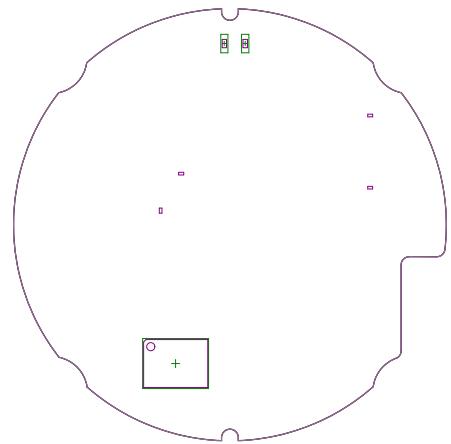


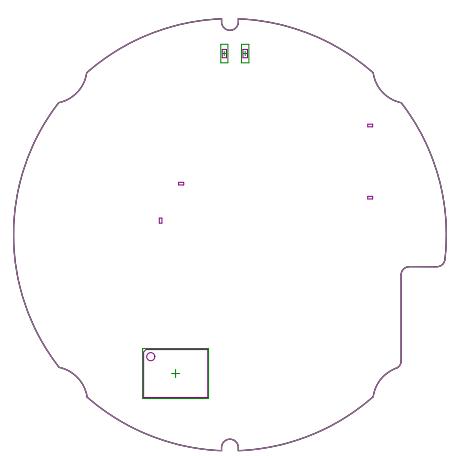


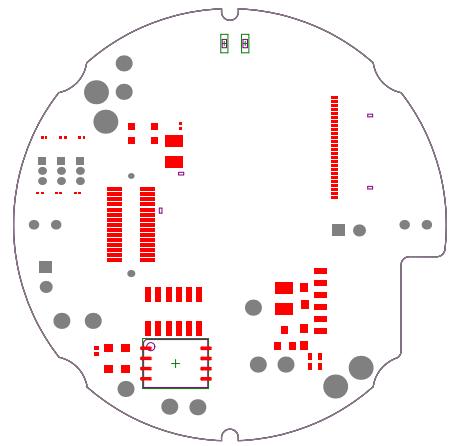


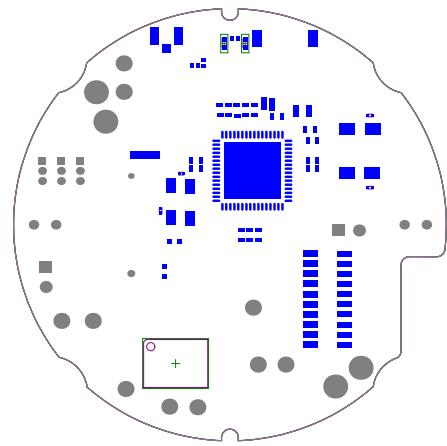


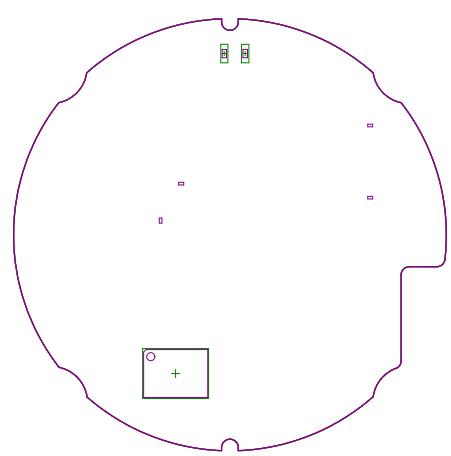












Fabrication / Assembly Notes

1. Material: Rigid
2. Number of electrical layers: 4
3. Trace / Space minimum: 5mil (all layers)
4. Thickness: 0.76mm (finished)
5. Finish: ENIG plating on exposed copper
6. Soldermask: per IPC-SM-840, color green registration within +/- 50um of circuit layer
7. Silkscreen: do print silkscreen on top and bottom layers
8. RoHS: parts shall be RoHS compliant as per European Union directive 2002/95/EC
9. Board must be lead free process compatible and able to withstand minimum of 5 cycles at 250 degrees celsius
10. All Test/QA/QC markings to be made on back side of PCB

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| 1 | Top Paste | | | | |
| 2 | Top Overlay | | | | |
| 3 | Top Solder | Solder Resist | 0.010mm | 3.5 | |
| 4 | Top Layer | Copper | 0.036mm | | |
| 5 | Dielectric 1 | FR-4 | 0.254mm | 4.2 | |
| 6 | PWR | Copper | 0.017mm | | |
| 7 | Dielectric 2 | | 0.254mm | 4.2 | |
| 8 | GND | Copper | 0.017mm | | |
| 9 | Dielectric 3 | | 0.127mm | 4.2 | |
| 10 | Bottom Layer | Copper | 0.036mm | | |
| 11 | Bottom Solder | Solder Resist | 0.010mm | 3.5 | |
| 12 | Bottom Overlay | | | | |
| 13 | Bottom Paste | | | | |

| Symbol | Hit Count | Finished Hole Size | Plated | Hole Type | Physical Length | Rout Path Length |
|--------|-----------|--------------------|--------|-----------|-----------------|------------------|
| ◊ | 1 | 0.700mm (27.56mil) | NPTH | Round | | |
| ☒ | 1 | 0.900mm (35.43mil) | NPTH | Round | | |
| ○ | 2 | 1.700mm (66.93mil) | NPTH | Round | | |
| ☒ | 2 | 2.100mm (82.68mil) | NPTH | Round | | |
| ◊ | 4 | 0.900mm (35.43mil) | PTH | Round | | |
| ☒ | 4 | 2.400mm (94.49mil) | PTH | Round | | |
| □ | 9 | 0.600mm (23.62mil) | PTH | Round | | |
| ▽ | 10 | 1.700mm (66.93mil) | PTH | Round | | |
| ▽ | 16 | 0.300mm (11.81mil) | PTH | Round | | |
| ■ | 174 | 0.200mm (7.87mil) | PTH | Round | | |
| | 223 Total | | | | | |

